

Proposed Amendments to the Claims:

Claim 1 (currently amended) ~~A temperature compensated attenuator device to compensate the effect of temperature changes in an electronic circuit comprising:~~

An attenuator device having at least two ports, the attenuator to compensate the effect of temperature changes in an electronic circuit, the device comprising:

a low temperature co-fired ceramic metal (~~LTCC-M~~) (LTCC) integrated package including a substrate having a pair of major surfaces;

a plurality of ~~layers~~ of thermistors and ~~insulators~~ embedded within the substrate, at least one of the thermistors comprising a sheet of thermistor material having a pair of major surfaces and a pair of electrodes formed on and laterally spaced apart by the major surfaces, the thermistor sheet layered with insulating layers and ~~electrically connected to form the attenuator device~~ the electrodes on the major surfaces interconnecting the thermistors, the thermistors forming the components of an attenuator in a temperature compensating circuit; and

at least three terminals forming the at least two ports, wherein one of the terminals comprises an input electrode connected to one of the thermistors, one of the terminals comprises an output electrode connected to at least one different thermistor, and one of the terminals comprises a common terminal.

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Claim 2 (original): A device according to claim 1 wherein each electrode comprises a first portion on one major surface, a second portion on the other major surface and one or more conductive vias connecting the first and second portions.

Claim 3 (original): A device according to claim 1 wherein the sheet of thermistor material has a thickness of about 0.001 inch or more.

Claims 4-6 (previously canceled)

Claim 10 (previously new): The device of claim 6 wherein the insulating layer comprises a ceramic substrate formed from organic binder and glass.

Claim 11 (previously new): The device of claim 1 wherein the attenuator comprises a circuit topology selected from the group consisting of pi ~~filter~~ attenuator, T ~~filter~~ attenuator, and bridged T ~~filter~~ attenuator.

Claim 12 (new): An electronic circuit comprising an amplifier and a device according to claim 1 having thermistors with temperature coefficients to compensate for temperature induced gain changes at the amplifier.

Claim 13 (new): An electronic circuit comprising a passive electronic circuit and a device according to claim 1, the temperature coefficients of the thermistors to compensate for changes in the passive circuit's loss with temperature.

Claim 14 (new): The device of claim 1 wherein at least one of the thermistors has a different temperature coefficient than another of the thermistors of the attenuator.

Claim 15 (new): The device of claim 1 wherein one thermistor has a positive temperature coefficient and a different thermistor has a negative temperature coefficient.